

HM4409-VB Datasheet

P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY							
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^d	Q _g (Typ.)				
- 30	0.011 at V _{GS} = - 10 V	- 13.5	29.5 nC				
- 30	0.015 at V _{GS} = - 4.5 V	- 11.6					

FEATURES

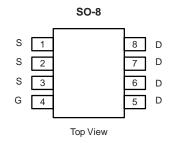
- Halogen-free
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

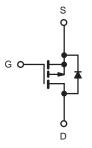


RoHS

APPLICATIONS

- Load Switch
- · Notebook Adaptor Switch





P-Channel MOSFET

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage	V_{GS}	± 20	v	
	T _C = 25 °C		- 13.5	
Continuous Proin Current /T = 150 °C	T _C = 70 °C		- 11.9	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	- 10.9 ^{a, b}	
	T _A = 70 °C		- 8.6 ^{a, b}	
Pulsed Drain Current	I _{DM}	- 50	Α	
Continuous Source-Drain Diode Current	T _C = 25 °C		- 4.1	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 2.2 ^{a, b}	
Avalanche Current	1 0411	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
	T _C = 25 °C		5.0	
Mariana Dama Dissination	T _C = 70 °C	P _D	3.2	w
Maximum Power Dissipation	T _A = 25 °C		2.7 ^{a, b}	vv
	T _A = 70 °C		1.7 ^{a, b}	
Operating Junction and Storage Temperature Rang	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W		
Maximum Junction-to-Foot	Steady State	R _{th,IF}	20	25	*C/VV		

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on T_C = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	In = - 250 HA		- 34		mV/ °C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			5.3			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1.4		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA	
Zoro Coto Valtorio Droin Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V			- 1	- 1 - 5 μΑ	
Zero Gate Voltage Drain Current		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
	_	V _{GS} = - 10 V, I _D = - 10 A		0.011		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 8 A		0.015			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 10 A		28		S	
Dynamic ^b							
Input Capacitance	C _{iss}			2550		pF	
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		455			
Reverse Transfer Capacitance	C _{rss}			390			
·	0	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 10 A		57	86		
Total Gate Charge	Q_g			29.5	45		
Gate-Source Charge	Q_{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -10 \text{ A}$		8		nC	
Gate-Drain Charge	Q_{gd}			22			
Gate Resistance	R _g	f = 1 MHz	0.5	2.2	4.4	Ω	
Turn-On Delay Time	t _{d(on)}			13	25		
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		12	24		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		40	70		
Fall Time	t _f	ĺ		9	18		
Turn-On Delay Time	t _{d(on)}			48	80	ns	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		92	160		
Turn-Off DelayTime	t _{d(off)}	$I_{D} \cong -10 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_{q} = 1 \Omega$		34	60		
Fall Time	t _f	1		19	35		
Drain-Source Body Diode Characteris	stics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1		
Pulse Diode Forward Current	I _{SM}	-			- 60	Α	
Body Diode Voltage	V _{SD}	I _S = -3 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	5 55		27	45	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	╡ <u>.</u>		16	27	nC	
Reverse Recovery Fall Time	t _a	$I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		12		ns	
Reverse Recovery Rise Time	t _b	1		15			

Notes:

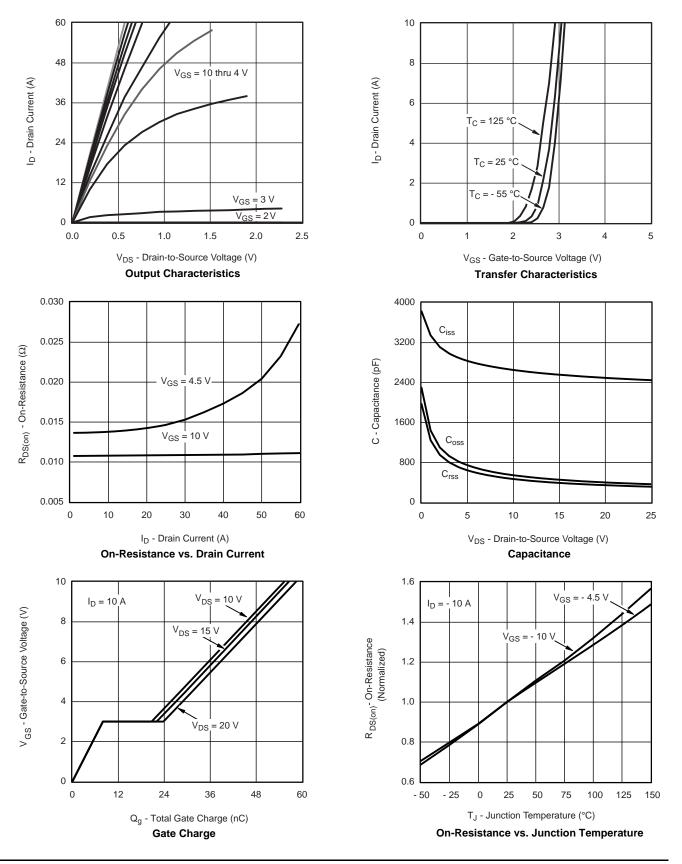
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

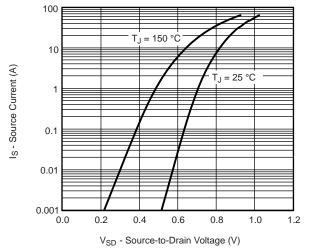


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

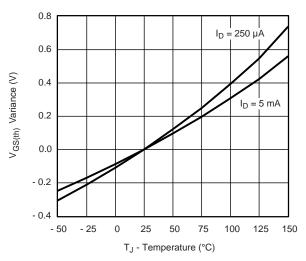




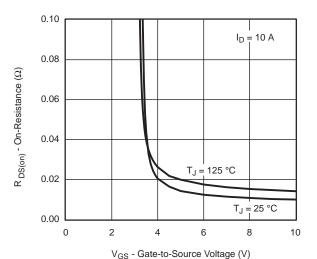
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



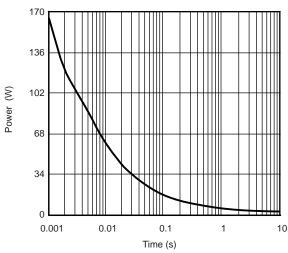
Source-Drain Diode Forward Voltage



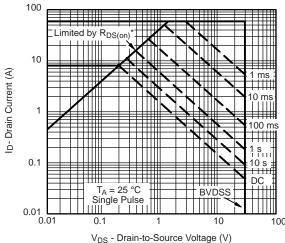
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

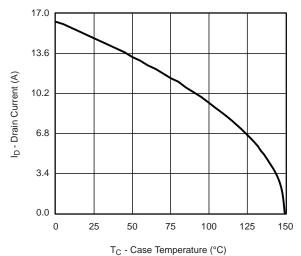


* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

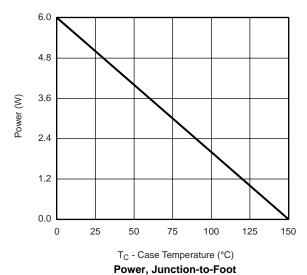
Safe Operating Area

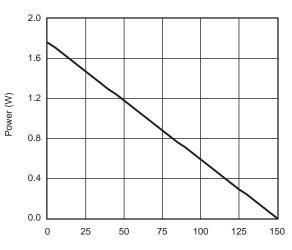


MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*



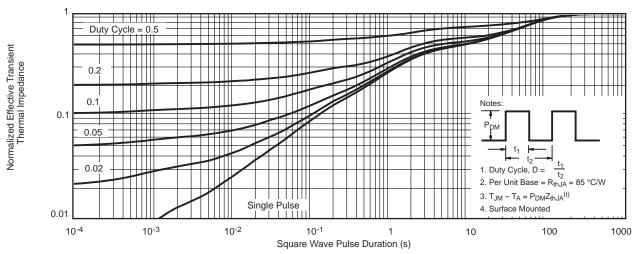


T_A - Ambient Temperature (°C) Power Derating, Junction-to-Ambient

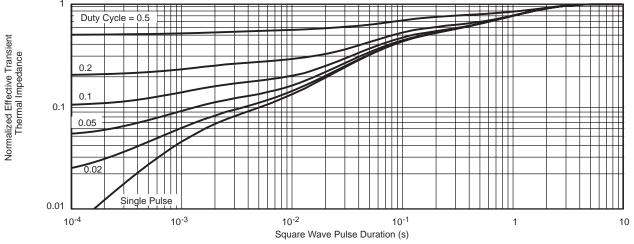
^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



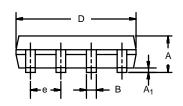
Normalized Thermal Transient Impedance, Junction-to-Foot

服务热线:400-655-8788 6



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







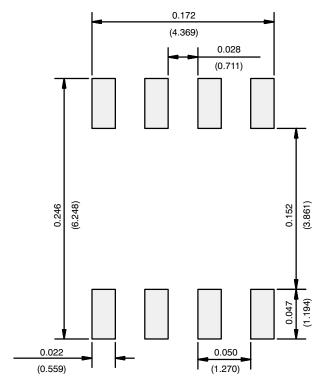
	MILLIN	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Pey I 11-Sep-06						

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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